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(19) **United States**(12) **Patent Application Publication****Yang et al.**(10) **Pub. No.: US 2022/0386506 A1**(43) **Pub. Date: Dec. 1, 2022**(54) **HEAT-SINK CHAMBERS****Publication Classification**(71) Applicant: **Hewlett-Packard Development Company, L.P.**, Spring, TX (US)(51) **Int. Cl.**
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G06F 1/20 (2006.01)(72) Inventors: **Hao-Wu Yang**, Taipei City (TW);
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Example implementations relate to heat-sink chambers. For instance, in an example a heat-sink can include a body including a first surface and a second surface, where the body defines: a chamber that extends from the first surface through a portion of a total thickness of the body; an opening in the second surface; and a channel that extends from the chamber through a remaining portion of the total thickness of the body to the opening to couple the chamber to the opening.

